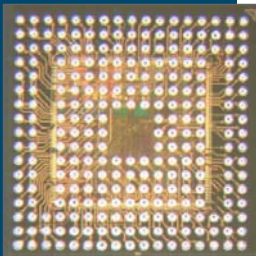
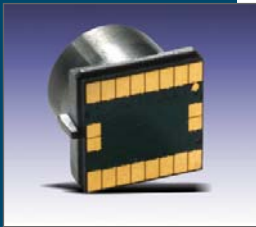
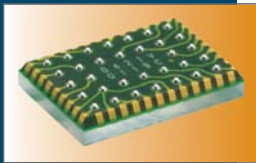


Advanced Packaging Update: *Market and Technology Trends*

Vol. 3, 2006



Volume 3 of the Advanced Packaging Update for 2006 features special coverage of embedded component packaging technology. Developments from General Electric, ACET, 3D Plus, Casio Micronics, and Freescale Semiconductor are discussed. The report also provides information on the latest developments in camera module technology, including Tessera's new SHELLCASE package. An update on strip testing is provided, including a discussion of its advantages and disadvantages and coverage of the companies that are using it. New developments in dicing technology for low-k and thin wafers are also discussed. Systems from ADT, ALSI, Disco, ESI, EO Technics, New Wave, Panasonic, Shibuya, Singulase, Synova, and Xsil are included, and the installed base for systems is reported and compared with conventional dicing blades. A new plasma dicing system from Panasonic is introduced.

Table of Contents

- 1 Economic Outlook
- 2 Embedded Components
 - 2.1 General Electric
 - 2.2 ACET
 - 2.3 3D Plus
 - 2.4 Casio Micronics
 - 2.5 Freescale Semiconductor
- 3 Camera Module Technology
- 4 Strip Test
 - 4.1 Strip Testing Advantages
 - 4.1.1 Strip Test in Production
 - 4.1.2 Amkor Technology
 - 4.1.3 Analog Devices
 - 4.1.4 Carsem
 - 4.1.5 MicroChip
 - 4.1.6 National Semiconductor
 - 4.1.7 STATSChipPAC
 - 4.1.8 STMicroelectronics
 - 4.1.9 Texas Instruments
 - 4.1.10 UTAC
- 5 Dicing for Low-k and Thin Wafers
 - 5.1 Laser Dicing
 - 5.2 Plasma Dicing

List of Figures

- 2.1. GE "Chips First" process.
- 2.2. EWLP process flow.
- 2.3. Freescale RCP process and example.
- 2.4. Product roadmap for RCP technology.
- 3.1. Camera modules.
- 3.2. Tessera SHELLCASE packages.
- 3.3. SHELLCASE® RT main process steps.
- 5.1. Plasma dicing process flow.
- 5.2. Chip strength test.

List of Tables

- 3.1. Camera Modules in Various Mobile Phones
- 4.1. Comparison of Throughput Variables for Different Handlers
- 4.2. Strip Test at Semiconductor Manufacturers
- 4.3. Strip Test at IC Package Contract Assembly Service Providers
- 5.1. Laser Dicing/Scribing Systems


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